

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet

1

of

2

Complete If Known

Application Number	Unknown
Filing Date	(Herewith)
First Named Inventor	Efren M. Lacap
Art Unit	Unknown
Examiner Name	Unknown
Attorney Docket Number	408204

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
gg	1	US-5,553,769	09-10-1998	Ellerson et al.	
	2	US- 4,604,644	08-05-1986	Beckham et al.	
	3	US- 5,316,205	05-31-1994	Melton	
	4	US- 5,918,792	07-06-1999	Stumpe et al.	
	5	US- 6,278,264	08-21-2001	Burstein et al.	
	6	US- 6,445,244	09-03-2002	Stratakos et al.	
	7	US- 6,400,126	06-04-2002	Zuniga et al.	
	8	US- 6,498,467	12-24-2002	Stratakos	
	9	US- 6,445,169	09-03-2002	Schultz et al.	
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	11	US- 6,462,522	10-08-2002	Burstein et al.	
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	13	US- 6,225,795	05-01-2001	Stratakos et al.	
	14	US- 3,429,040	02-25-1989	Miller	
	15	US- 3,401,126	09-10-1988	Miller et al.	
	16	US- T955,008	02-01-1977	Gregor et al.	
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		US-			
		US-			
		US-			

FOREIGN PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				

Examiner
Signature

Jonathan J.

Date
Considered

6/18/05

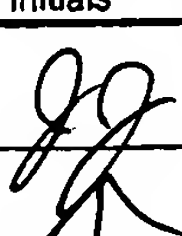
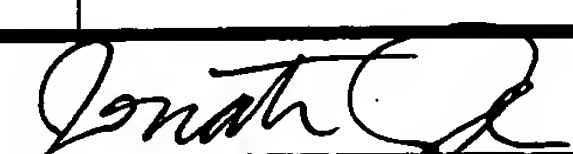
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		First Named Inventor	Efren M. Lacap		
		Group Art Unit	Unknown		
		Examiner Name	Unknown		
Sheet	2	of	2	Attorney Docket Number	408204

OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS				
Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²	
 ↓	1	Figures 1, and 3-8 from "Oki technical Review", http://www.oki.com/en/otr/html/nf/ , February 19, 2003, 5 pages		
	2	"Flip chip photographs of flip chip bumps, flip chip assemblies, flip chip interconnections", Flipchips dot com, http://www.flipchips.com/photos.html , February 13, 2003, 3 pages		
	3	"Flip-chip Packaging: a 32-Year-Old Infant Grows Up", Chip Scale Review Online, http://www.chipscalereview.com/issues/0701/fi_01.html , July, 2001, pp. 1-4		
	4	"Flip-chip Packaging: a 32-Year-Old Infant Grows Up", Chip Scale Review Online, http://www.chipscalereview.com/issues/0701/fi_02.html , July, 2001, pp. 1-5		
	5	"The Emerging Copper Revolution Will Impact ICs with Critical Dimensions 100nm", Chip Scale Review Online, http://www.chipscalereview.com/issues/0301/techReport.html , March, 2001, pp. 1-3		
	6	"Making Microchips", http://www.glenco.com/norton/n-instructor/updates/2000/21100-7.html , February 19, 2003, pp. 1-4		
	7	"Process Defect Guides", ppm-monitoring.com, http://www.thepdfshop.com.uk/ppm/asp/wave.asp , July 2, 2003, 4 pages		
	8	"300mm Wafer Bumping", Technology Publishing - A division of Montgomery Research Europe Ltd., http://www.future-fab.com/documents.asp?grID=217&d_ID=1338 , July 1, 2003, 6 pages		
	9	XICOR, "CSP Packaging Technology ("B" Package Option)", Revised March, 2003, 11 pages, XICOR, Milpitas, CA		
	10	JASPER, JORG, "From Direct Chip Attach to Wafer Level CSP - A Modular Approach to Serve Customer Needs", 5 pages, EM -Marin S.A. <i>no date avail.</i>		
	11	BICE, SHANNON B. and LI, YUZHUO, "Chemical Mechanical Polishing (CMP) for Computer Chip Manufacturing", 3 pages. <i>no date avail</i>		
	12	ELENIUS, PETER, "The UltraCSP™ Wafer Scale Package", 6 pages, Flip Chip Technologies, Phoenix, AZ <i>no date avail.</i>		
	13	"STAYCHIP™ 3075F Underfill for Handheld Electronic Devices & System-in-Package", 15 pages, Cookson Electronics Semiconductor Products, Alpharetta, GA <i>no date avail</i>		
	14	DURAH, DR. HAMIT, "Chip-on-Foil: An Emerging Technology for Display Driver Electronics", October 10, 2002, 33 pages, Phillips Semiconductors Zurich		
	15	FJELSTAD, JOSEPH, "Wafer Level Packaging of Compliant CSPs Using Flexible Film Interposers", HDI Magazine, Spring 1999, 6 pages		
	16	"Flip Chip Packaging for SRAM", Copyright 1999, 2 pages, IBM USA		
Examiner Signature			Date Considered	6/18/05

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